

What is claimed is:

1. An optical module comprising:

an optical subassembly including a semiconductor optical device;

5 a housing including a base and a cover, the base having a bottom surface thereof, and the optical subassembly being provided between the base and the cover;

a support being in contact with the optical subassembly, the support being disposed on the bottom surface of the base; and

10 a thermal sheet provided between the cover and the support.

2. The optical module according to claim 1, wherein the support includes a first leg portion, a second leg portion and a bridge connecting the first and second leg portions with each other, the cover and the bridge sandwiching the thermal sheet therebetween, and

20 the optical subassembly is provided between the first and second leg portions.

3. The optical module according to claim 2, wherein the first and second leg portions are in contact with the optical subassembly with solders provided between the optical subassembly and the first and second leg portions, respectively.

4. The optical module according to claim 1, wherein the optical subassembly includes an outer surface and a stem for mounting the semiconductor optical device, and

5 wherein the support includes a first leg portion, a second leg portion, a bridge connecting the first and second leg portions with each other, and a finger curved so as to be in contact with the outer surface of the stem, the first and second leg portions providing the
10 optical subassembly therebetween, and the thermal sheet being provided between the bridge and the cover.

5. The optical module according to claim 4, wherein the outer surface of the optical subassembly is spaced from the bridge.

15 6. The optical module according to claim 4, wherein the finger is in contact with the stem with a solder provided between the stem and the finger.

7. The optical module according to claim 4, wherein the support has another bridge for securing the
20 finger with the first and second leg portions.

8. The optical module according to claim 7, wherein a level of the bridge relative to the bottom surface of the base is greater than a level of the other bridge relative to the bottom surface of the base.

25 9. The optical module according to claim 7, wherein the other bridge is spaced from the outer surface

of the stem.

10. The optical module according to claim 7,
wherein the support further includes first and second
arms provided on sides of the first and second leg
5 portions for connecting the other bridge to the first
and second leg portions, the first and second arms being
connected with each other by the other bridge.

11. The optical module according to claim 10,
wherein the other bridge has an inner side facing to
10 the bridge, the finger being provided on the inner side.

12. The optical module according to claim 11,
further comprising a circuit board provided in the
housing,

wherein the optical subassembly has a lead
15 terminal connected to the circuit board.